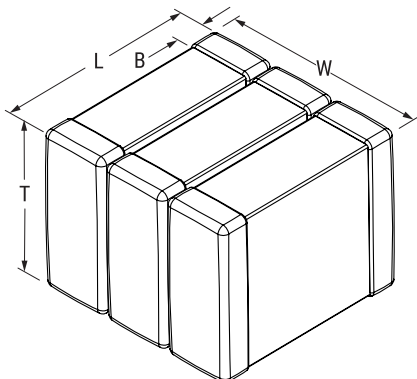


KONNEKT KC-Link, Ceramic, 0.45 uF, 10%, 650 VDC, COG, 3-Chip Low Loss Orientation.



| Dimensions | |
|------------|-----------------|
| L | 9.3mm +/-0.6mm |
| W | 7.7mm +/-0.6mm |
| T | 10.2mm +/-0.4mm |
| B | 1.27mm +/-0.4mm |

| Packaging Specifications | |
|--------------------------|------------|
| Packaging: | T&R, 180mm |
| Packaging Quantity: | 50 |

| General Information | |
|---------------------|--|
| Series: | KONNEKT KC-Link |
| Style: | KONNEKT |
| Description: | KC-LINK with KONNEKT, SMD, MLCC, Ultra-Stable, Class I |
| Features: | Ultra-Stable |
| RoHS: | Yes |
| Termination: | Tin |
| AEC-Q200: | No |
| Component Weight: | 3.3 g |
| Notes: | 3-Chip Low Loss Orientation. |
| Chip Size: | 3640 |
| MSL: | 1 |

| Specifications | |
|---|------------------------|
| Capacitance: | 0.45 uF |
| Measurement Condition: | 1 kHz 1.0Vrms |
| Capacitance Tolerance: | 10% |
| Voltage DC: | 650 VDC |
| Dielectric Withstanding Voltage: | 845 VDC |
| Temperature Range: | -55/+150°C |
| Temperature Coefficient: | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC): | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor: | 0.1% 1 kHz 1.0Vrms |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 2.222 GOhms |

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